NOTES:

1. RMA compliant certification or material declaration required.
2. MATERIAL
   a. J5410 or equivalent. Material must conform to UL94-V-0.
   b. Use MTE Copper as specified in the cross section diagram.
   c. Overall metal to metal thickness as specified in the cross section.
3. DRILLING:
   a. Diameters in drill table are finished hole sizes +/- .003 in.
   b. Unless otherwise specified, in drill table.
   c. Drilling allowed on entry of Vias on every trace layer.
4. PLATING:
   a. Copper plating in thru-holes .001 in.
5. MARKING:
   a. Silkscreen in white non-conductive epoxy ink on primary side of the board or both sides if applicable.
   b. Fabricator to place date code and lot code on secondary side in etch (preferred) or silkscreen.
6. FINISHING:
   a. Soldermask primary and secondary side of board using liquid photoseparable
      mask material over Solder Copper per IPC-J-840. Mask artwork provided.
      are 1:1 soldermask color 448E0E4.
7. FINISH:
   a. Shall be electrolytic nickel/gold, electroless nickel / immersion gold (ENIG).
   b. Nickel thickness: 1.0 ± 0.2 micrometers per BGA pad.
   c. Gold thickness: 3.0 ± 0.2 micrometers per BGA pad.
   d. Boards shall be purchased from UL recognized vendors only and shall be
      marked in copper on secondary side of board with vendors UL system.
5. Flammability rating 94-V0, date code (MMYY), and UL compliant symbol.
   e. Manufacture board to be in accordance with performance standard
      IPC-A-601A/601A CLASS 2 to board to be inspected per IPC-608-A CLASS 2.
8. MAXIMUM WRAP OR TRIM SHALL NOT EXCEED .002 in.
9. TESTING:
   a. Fabricator to add test structures or coupons as needed.
   b. 1. T-Line impedance to be tested or guarantee within 10% if specified in
      the cross section. Tolerance to be +/- 0.5% unless otherwise specified.